MASKLESS LITHOGRAPHY SYSTEM

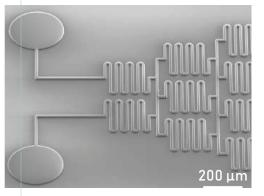
POLOS pPrinter

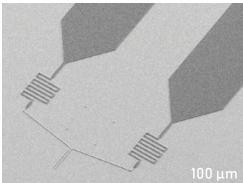
The POLOS μ Printer is a maskless lithography equipment for rapid-prororyping, based on a μ LCD projection technology, compatible with a wide range of resists and substrates. Our system can produce any 2D shapes at micron resolution without the need for a hard-mask.

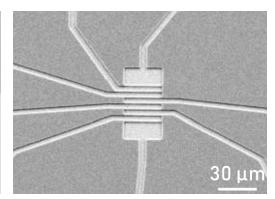
Key features

- Writing resolution down to 2 µm
- Adjustable writing field and resolution with exchangeable objectives
- Compatible with CAD files or bitmap images
- Compatible with g-line photoresists
- Compatible with a wide range of substrates (silicon, glass, metal, plastic, ...)
- Compatible with any sample size up to 4" wafer
- Camera feedback for alignment steps









Key benefits

- Time and money saving due to the absence of a hard-mask
- Intuitive alignment method with direct overlay of the design on the sample
- Table-top with very small foot print
- Technology well suited for microelectronics, 2D-materials, microfluidics, optoelectronics, opties or any other 2D microfabrication application



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POLOS pPrinter

SPECIFICATIONS



Microfabrication system

Light source	Exposure: 435 nm; alignment: 525 nm	
Minimum feature size	Adjustable from 2 to 23 μm	
Alignment resolution	Down to 1 µm/cm ²	
Maximum exposure area	75 x75 mm ²	
Substrate size	Up to 4" wafers	
System dimensions	W: (36 cm); D: (36 cm); H: (60 cm)	

Software package

All-in-one PC	With Win 10, 24" full HD			
SFTprint software	Machine control, step-and-repeat, automatic dose test, stitching, alignment			
SFTconverter	Convertion of standard formats (gdsii, dxf, cif, oas) to bitmap images. CAD software included			

Options and accessories

- Multiple-sample hold er (glass-slide, 4" water, ...)
- Objectives (see below)
- Manual or motorized Z stage with tilt correction
- Manual rotation stage (360°)

Objective	1X	2.5X	5X	10X
Writing field (mm)	13.6 x 7.7	5.4 x 3.0	2.7x 1.5	1.35 x 0.75
Smallest feature (µm)	23	8	4	2